

ABSTRACT OF THE DISCLOSURE

[0056] Embodiments of the present invention provide a method of joining two semiconductor wafers face-to-face using an interposer. One embodiment includes a wafer stack comprising a first wafer having a first metal pattern disposed on a top surface, a second wafer having a second metal pattern disposed on a top surface, and an interposer disposed between the top surface of the first wafer and the top surface of the second wafer, the interposer having a pattern of metal vias disposed in a cured thermosetting plastic, the pattern of metal vias being aligned with and electrically coupled to the first metal pattern and the second metal pattern.